PRESS RELEASE

Contact: Jan Vardaman
          (512) 372-8887

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TechSearch International Analyzes New Automotive Packaging Trends

More than 80 companies are developing autonomous vehicles and many more are involved in providing sensors and computational systems for advanced driver assistance systems (ADAS). System design, package choices, materials, and process integration are critical to the successful implementation of the new safety features that are part of ADAS and will ultimately be a part of autonomous driving. ADAS requires the use of cameras, light detection and ranging (LIDAR), radar, and other sensors, as well as communication systems and fast processing capability. The potential use of artificial intelligence or machine learning to provide the analytics enabling safety features is driving the adoption of advanced packaging and heterogeneous integration. Different combinations of sensors will be used in each vehicle and the particular combinations will be determined by each carmaker.

TechSearch International's *New Frontier's in Automotive Electronics Packaging* examines the packaging choices for these sensors. The report answers key questions: What type of semiconductor packages are used for image sensors, radar, ultrasonic, and LIDAR? Where are fan-out wafer level packages and flip chip interconnects being adopted? How do package reliability requirements differ from other applications? What are future challenges for new package adoption? The report also examines trends in interconnect technology such as the adoption of copper wire bonding and copper clip. Packaging trends in the powertrain for electric and hybrid vehicles are also analyzed. Automotive specific offerings from OSATs and IC package substrate makers are described.

The report's five-year market forecast focuses on new packages introduced as a result of ADAS adoption. Projections for the use of image sensors are presented. Unit volumes for radar modules with FO-WLP are provided. A market forecast for processors used in sensor fusion is included. Package types used in electric powertrains and a five-year forecast in unit volumes are provided.

The 110-page report provides full references and an accompanying set of 94 PowerPoint slides.

TechSearch International, Inc., founded in 1987, is a market research leader specializing in technology trends in microelectronics packaging and assembly. Multi- and single-client services are offered. TechSearch International professionals have an extensive network of more than 18,000 contacts in North America, Asia, and Europe. For more information, contact TechSearch at tel: 512-372-8887 or visit www.techsearchinc.com. Follow us on twitter @Jan_TechSearch

4801 Spicewood Springs Road • Suite 150   Tel: 512-372-8887 • Fax: 512-372-8889
Austin, Texas 78759   tsi@techsearchinc.com